General Description

The WSF40P03 is the highest performance trench P-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSF40P03 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

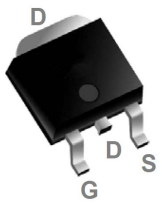
Product Summery

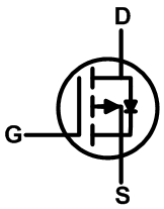
BVDSS	RDSON	ID
-30V	18mΩ	-40A

Applications

- Power Magagement in Desktop
- DC/DC Converters.
- Load Switch

TO-252 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	±25	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ -10V	-40	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ -10V	-25	A
I_D@T_A=25℃	Continuous Drain Current, V_{GS} @ -10V	-9.6	A
I_D@T_A=70℃	Continuous Drain Current, V_{GS} @ -10V	-7.7	A
I_{DM} [a]	Pulsed Drain Current	-160	A
E_{AS} [b]	Single Pulse Avalanche Energy	28	mJ
I_{AS} [b]	Avalanche Current	-20	A
P_D@T_A=25℃	Total Power Dissipation	2.5	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$ [c]	Thermal Resistance Junction-Ambient	---	50	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	2.9	℃/W

Note a：Pulse width limited by max. junction temperature.
Note b：UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T_j=25°C).
Note c：Surface Mounted on 1in^2 pad area.

Electrical Characteristics (T_J=25℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=-250uA	-30	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=-1mA	---	-0.022	---	V/℃
$R_{DS(ON)}$ [d]	Static Drain-Source On-Resistance[2]	V_{GS}=-10V , I_D=-20A	---	15	18	mΩ
		V_{GS}=-4.5V , I_D=-15A	---	20	26	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =-250uA	-1.2	-1.6	-2.5	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-24V , V_{GS}=0V , T_J=25℃	---	---	-1	uA
		V_{DS}=-24V , V_{GS}=0V , T_J=55℃	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	3.5	---	Ω
Q_g	Total Gate Charge	V_{DS}=-15V, V_{GS}=-4.5V, I_{DS}=-20A	---	11	---	nC
Q_{gs}	Gate-Source Charge		---	5	---	
Q_{gd}	Gate-Drain Charge		---	5	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=-15V, R_L=15Ω, I_{DS}=-1A, V_{GEN}=-10V, R_G=6Ω	---	11	20	ns
T_r	Rise Time		---	10	18	
$T_{d(off)}$	Turn-Off Delay Time		---	39	70	
T_f	Fall Time		---	29	53	
C_{iss} [e]	Input Capacitance	V_{GS}=0V, V_{DS}=-15V, Frequency=1.0MHz	---	1256	1633	pF
C_{oss} [e]	Output Capacitance		---	187	---	
C_{rss} [e]	Reverse Transfer Capacitance		---	115	---	

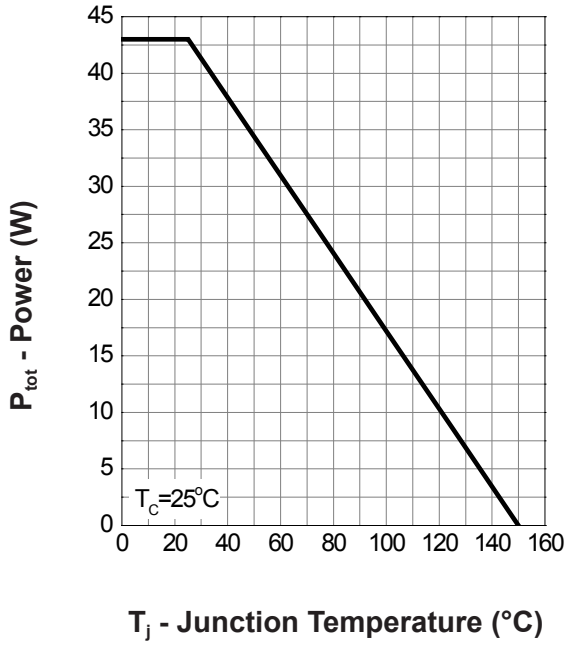
Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	-20	A
V_{SD} [d]	Diode Forward Voltage	V_{GS}=0V , I_S=-1A	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	I_F=-20A , dI/dt=100A/μs	---	12	---	nS
Q_{rr}	Reverse Recovery Charge		---	3.5	---	nC

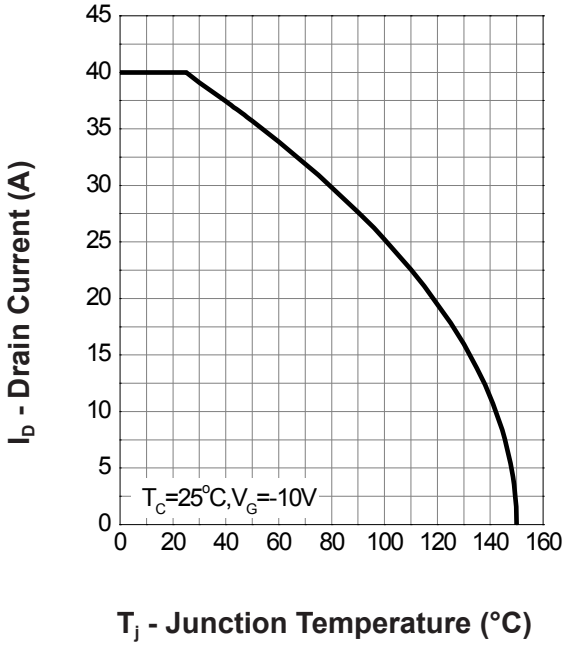
Note d：Pulse test ; pulse width≤300μs, duty cycle≤2%.
Note e：Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

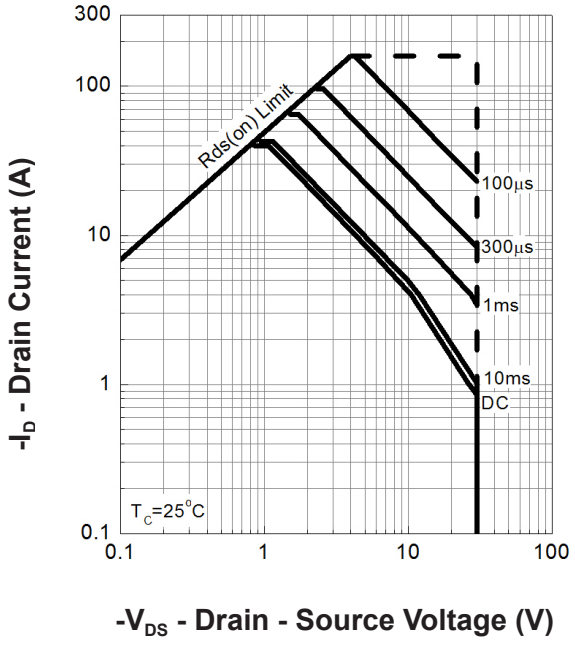
Power Dissipation



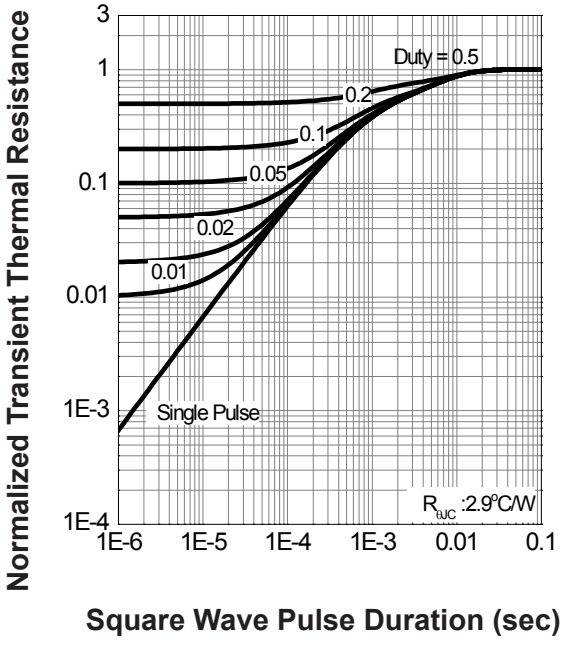
Drain Current



Safe Operation Area

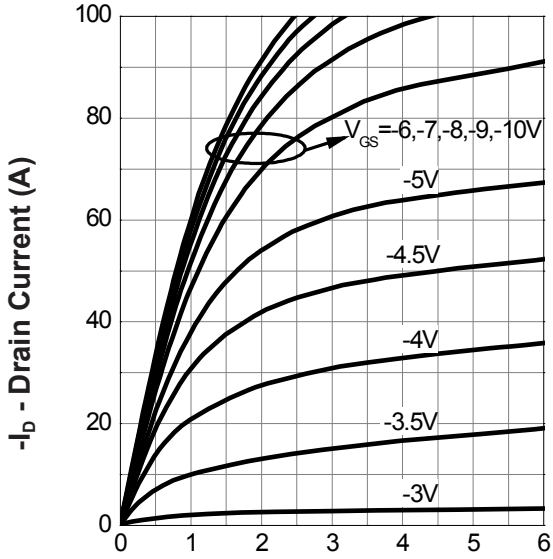


Thermal Transient Impedance



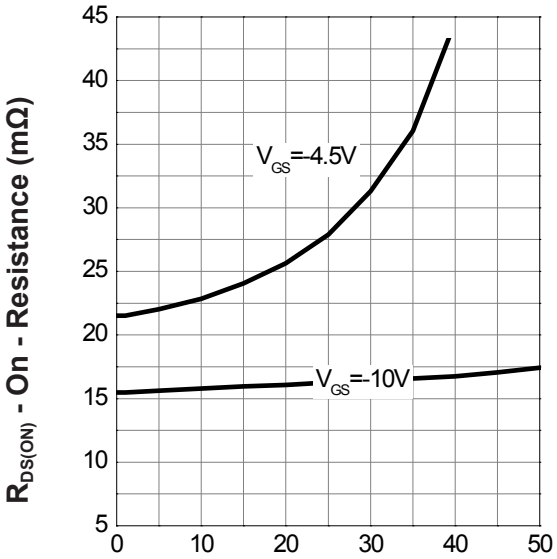
Typical Operating Characteristics(Cont.)

Output Characteristics



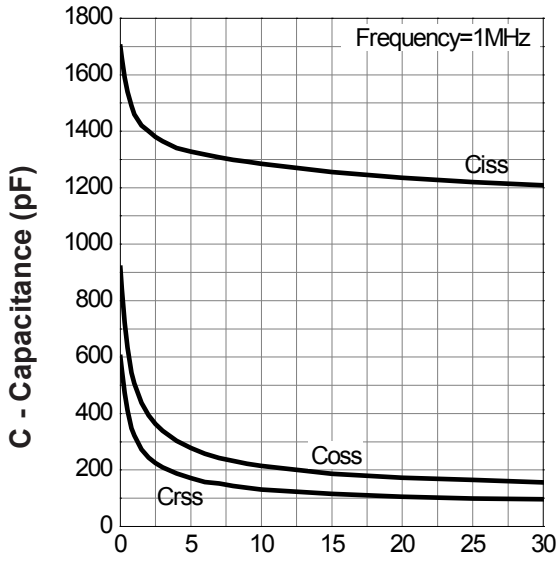
-V_{DS} - Drain - Source Voltage (V)

Drain-Source On Resistance



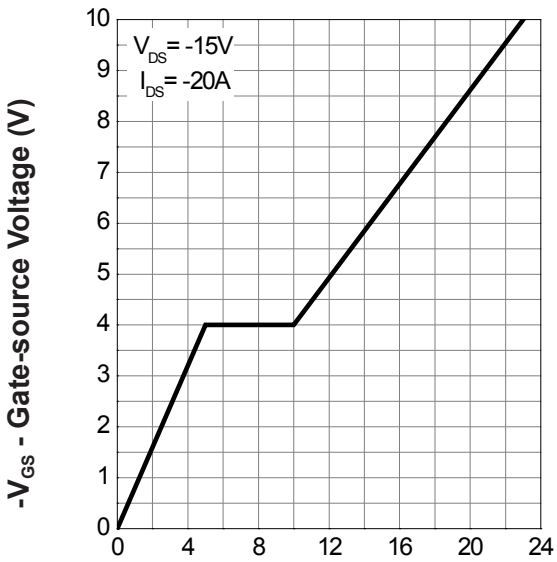
-I_D - Drain Current (A)

Capacitance



-V_{DS} - Drain-Source Voltage (V)

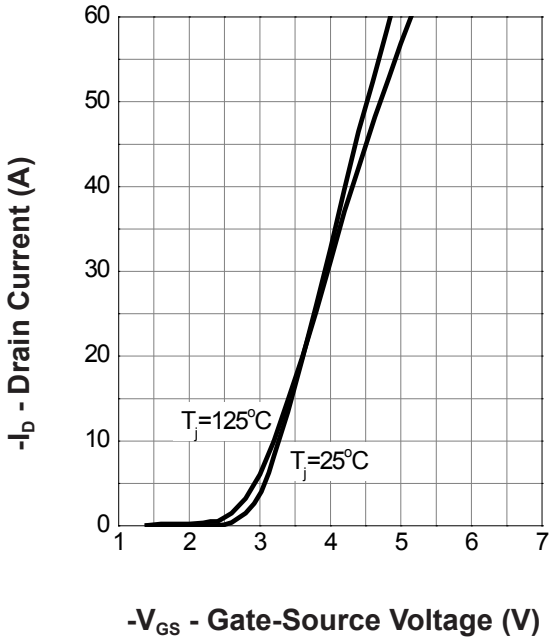
Gate Charge



Q_G - Gate Charge (nC)

Typical Operating Characteristics(Cont.)

Transfer Characteristics



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